

SUBSTITUTE SPECIFICATION – CLEAN VERSION

Attorney Docket No. 1406/334

ABSTRACT

The invention relates to a heat-conducting coating of electronic circuit assemblies (102), comprising a
5 coating agent (100), which encloses the electronic circuit assembly (102) and which is electrically insulating, with dispersed particles in the coating agent (100) which have a high thermal conductivity, whereby the particles dispersed in the coating agent
10 (100) are embodied as nanoelements (101).